

Reflow- System FCV 35

For Reflow Soldering and Curing Processes in the Electronic Industry



Features:

- Seven independently controllable zones
- Two Forced Convection Reflow zones
- Nominal Temperature 350°C
- Heater is installed in front of Ventilator, therefore very good mixture of air and high temperature uniformity
- High heat transfer of air to product due to high velocity (Temperature uniformity app. +/-2°C)
- Cyclon Flux Condensation
- Exhaust duct on rear side
- Optional Medium Wave IR Emitters with Gold Plating can be installed in the heating zones
- IR-Zone-Controlled by Pilot Emitter

Process description:

The Reflow System is designed to reflow lead free solder paste or cure adhesive in order to fix the components on the board. .

Due to modular Design, the System can be equipped with pure air convection modules, pure IR modules or a combination of both heat methods!